ASSOCIATION CONNECTING LECTRONICS INDUSTRIES	ockburn, Illinois, A	ll rights reserved ur ations.	nder both	This docume evel parts, t	ent is a declaration entities of the declaration entities	on of the substancompasses all	ances within the manufactul lower level materials for	urer listed in which the m	tem. Note: if nanufacturer	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form Typ. http://www.ipc.org/IPC-175x Distribute			Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg Information					on			
Supplier Information												
ompany name* Company unique ID				Unique ID Authority				Respons	Response Date*			
onsemi									2023-06-08			
Contact Name	Title - Contact]	Phone - Contact*			Email -	Email - Contact*			
Product-Env-Stewards	Product Enviro Compliance				NA			Produc	Product-Env-Stewards@onsemi.com			
Authorized Representative*	horized Representative* Title - Representative			Phone - Representative*				Email -	Email - Representative*			
Product-Env-Stewards Product Enviro Compliance				NA				Produc	Product-Env-Stewards@onsemi.com			
Requester Item Number Mfr	Item Number	Mfr Item Name			Effective Date	Version	Manufacturing Site	,	Weight*	UOM	Unit Type	
NCV	891130PD50R2G 2MHz SMPS Hybri		rid LDO		2023-06-08		PH1		61.64	mg	Each	
Manufacturing Proccess Information						-						
Terminal Plating / Grid Array Material	Terminal Base Alloy J-		-STD-020 MSL	Rating	Peak Process Body Temperatur		perature Max Time at Pea	k Temperat	ure Numb	er of Reflow Cyc	eles	
Matte Tin (Sn) - annealed CU Alloy 2				260	С	30	secon	ids 3				
Comments												
ATTENTION: MSL 2 Rated item requires Dry Pa	ck (after electrical	test)										
for more information regarding material composit	ion please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		nium (Cr6+), Polybro	ominated Biphenyls (PBB), Polybron	dmium and quantity limit of 0.1% by mass (100 minated Diphenyl Ethers (PBDE), and Bis(2-eth	
cadmium, hexavalentchromium, polybrominate contains a RoHS restricted substance inexcess encompass all such components. Supplier certif as of the date that Supplier completes this form Company acknowledges that Supplier may hav independently verified information provided by certification in this paragraph. If the Company a	ed biphenyls and/or polybrominated dip of an applicable quantity limit, please ir ies that it gathered the information it pro- .Supplier acknowledges that Company e relied on informationprovided by othe v others, Supplier agrees that, at a minin and the Supplier enter into a written agre pource of the Supplier's liability and the	henyl ethers (each a " ndicate below which, i ovides in this form us will rely on this certifiers in completing this num, itssuppliers have eement with respect to Company's remedies	RoHS restricted substance") in exce if any, RoHS exemption you believe ing appropriate methods to ensure if ication in determining the complian form, and that Supplier may not have e provided certifications regarding the to the identified part, the terms and co for issues that arise regarding inform	ce of its products with European Union membe	ove. If a homogeneous material within the part er level components, the declaration shall l correct to the best of its knowledge and belief, r state laws that implement the RoHS Directive. wever, in situations where Supplier has not tions are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 1 - Item(s)	does not contain RoHS restricted substa	ances per the definitio	on above	Supplier Acceptance	* Accepted
Exemption: If the declared item does not con applicable exemptions.	ntain RoHS restricted substances per	the definition above	except for defined RoHS exempti	ons, then select the corresponding response i	n the RoHS Declaration above and choose all
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required fin Requester) and click on Submit Form to have	elds on all pages of this form. Select the form returned to the Requester	he "Accepted" on th	e Supplier Acceptance drop-down	. This will display the signature area. Digital	lly sign the declaration (if required by the
Supplier Digital Signature Ra	stislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

sigma range of distribution unless otherwise noted).								
Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.69	mg	Supplier	Silicon (Si)	7440-21-3		0.69	mg
Die Attach	0.5	mg	Supplier	Silver (Ag)	7440-22-4		0.375	mg
			Supplier	Epoxy resins	129915-35-1		0.125	mg
Lead Frame 2	29.69	mg	Supplier	Silver (Ag)	7440-22-4		0.6235	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0594	mg
			Supplier	Iron (Fe)	7439-89-6		0.7423	mg
			Supplier	Copper (Cu)	7440-50-8		28.2649	mg
Mold Compound-Black	28.58	mg		Epoxy resin	proprietary data		1.429	mg
			Supplier	Phenolic Resin	Proprietary Data		1.429	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		0.5716	mg
			Supplier	Carbon Black (C)	1333-86-4		0.1429	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		25.0075	mg
Plating	1.89	mg	Supplier	Tin (Sn)	7440-31-5		1.89	mg
Wire Bond - Au	0.29	mg	Supplier	Gold (Au)	7440-57-5		0.29	mg

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3